

# OL-PCF8811MU

Wire bond die; 248 bonding pads

10 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	U (upper)
<b>Package type descriptive code</b>	UC
<b>Package type industry code</b>	UC
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	X (other)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	14-12-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	12.14	-	mm
E	package width	-	-	1.86	-	mm
e	nominal pitch	-	-	70	-	µm
n <sub>2</sub>	actual quantity of termination	-	-	248	-	



## 2. Package outline

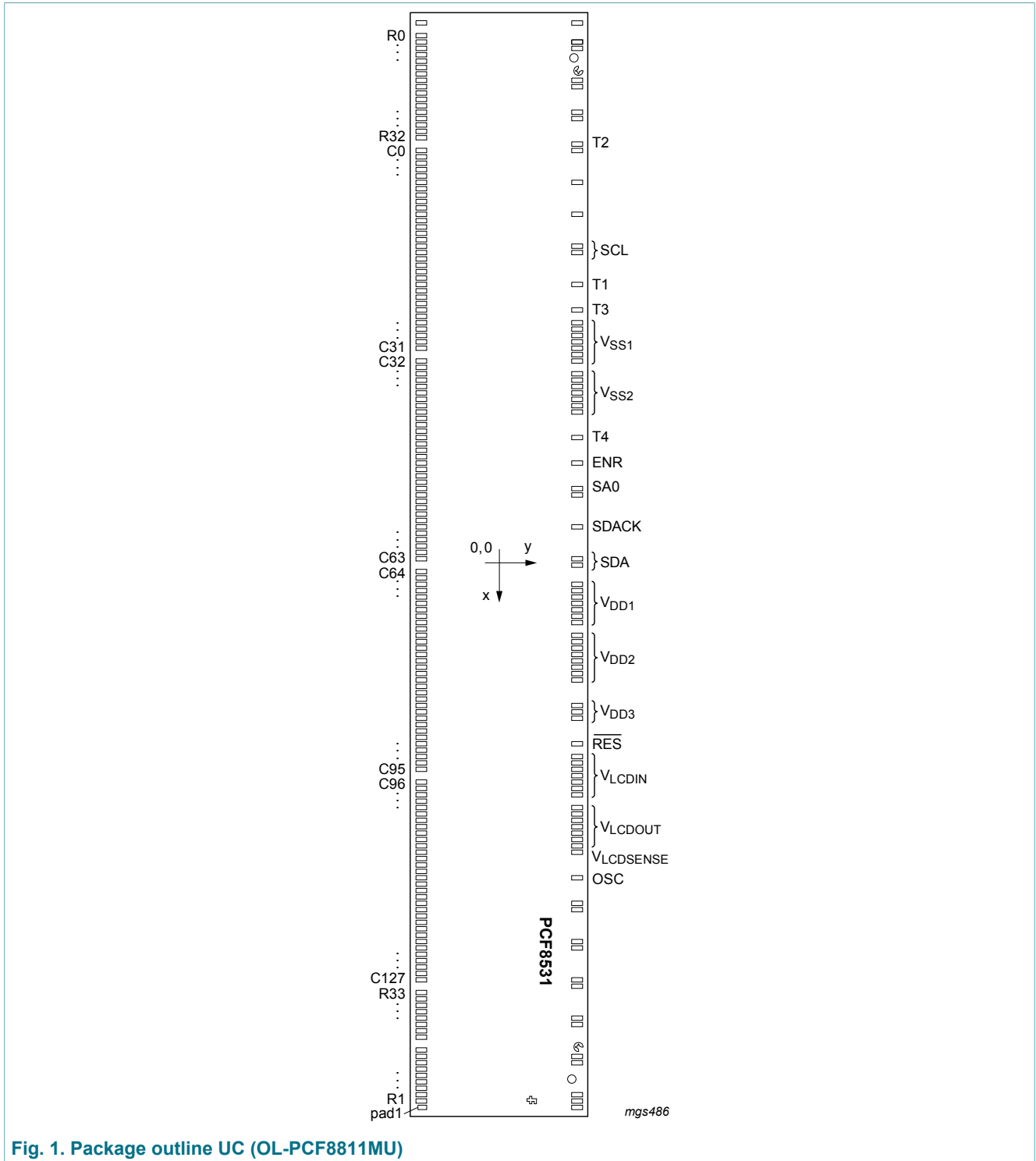


Fig. 1. Package outline UC (OL-PCF8811MU)

### 3. Legal information

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Date of release: 10 February 2016

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